	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Comment
1	BRS	L1		1	high nearl impurity nearl tantalum	USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM TDB	2002/11/0 7 17:20	
2	BRS	L2		141		USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 17:20	
3	BRS	L3		12	(high nearl purity nearl tantalum) near15 (weight)		2002/11/0 7 17:26	
4	BRS	L4	1	_2 t	(purity nearl lantalum) near15 I (weight)		2002/11/0 7 17:27	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Comment s		
5	BRS	L5		653	(tantalum) near15 (weight) near15 (metal\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 17:28			
6	BRS	L6		4	(tantalum) near15 (weight) near15 (metallic near3 impurities)	USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 17:31			
7	BRS	L7		85	(tantalum) near15 (weight) near15 (metallic)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2002/11/0 7 17:31			
8	BRS	L10	(*)	3 (n	(tantalum) near15 (weight) near15 (metallic) near10 (tungsten or nolybdenum) near15 (ppm)		2002/11/0 7 17:33			

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	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Comment s	
9	BRS	L8		40	(tantalum) near15 (weight) near15 (metallic) near10 (tungsten or molybdenum)	USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 17:55		
10	BRS	L1:	1	2745		USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 17:55		
11	BRS	L13	3		"Ta2O5" near10 (weight) near10 (metal\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2002/11/0 7 17:57		
12	BRS	L14	C)	"Ta2O5" near10 (weight) near10 (metallic)		2002/11/0 7 17:57		

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Comment
13	BRS	L15		0	"Ta205" near10 (weight) near10 (tungsten or molybdenum)	USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 17:57	
14	BRS	L12			"Ta2O5" near10 (weight)	USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 18:03	
15	BRS	L16	4		"Ta.sub.20.sub.5" near10 (weight)	USPA T; US-P GPUB; EPO; JPO; DERW ENT; IBM_ TDB	2002/11/0 7 18:03	

	บ	1	Document ID		Current OR	Pages	Issue Date
1	×		20020132388	Tantalum sputtering target and method of manufacture	438/77	11	20020919
2			B1	Tantalum sputtering target and method of manufacture	438/77	12	20011127
3			US 6323055 B	Highly pure tantalum preparation method for use in manufacture of electronic capacitors, bulk capacitors, thin film capacitors		12	20020611

11/07/2002, EAST Version: 1.03.0002

	U	1	Document ID	Title	Current OR	Pages	Issue Date
1	×		JP 2000165001 A	DIELECTRIC CIRCUIT BOARD		6	20000616
2		:	US 5188990 A	Low temp. metal oxide glass sealing compsn., for semiconductor packages, etc comprise tellurium oxide, vanadium oxide and other metal oxide(s) pref. niobium-, zirconium-and/or zinc-oxide(s)		6	19930223
3			JP 55060041 A	Infrared spectrum transmitting glass - contains oxides of germanium, aluminium, tantalum, and barium, opt. together with other oxides		3	19800506
4			DE 2844558 A	Stable electrodes, esp. anodes for electrolysis in acid medium - having coating of insol. metal tungstate, tantalum oxide and noble metal oxide		22	19790510